| ASSOCIATION CONNECTING<br>ELECTROMICS INDUSTRIES® | PC. Bannockł             | ourn, Illinois, A               | ll rights reserved utions. | under both              | This docume<br>level parts, t  | ent is a declarati<br>he declaration e | on of the su | ibstances v<br>s all lower           | vithin the manufactu<br>level materials for v | urer listed which the | item. Note:<br>manufactur       | if the item is an as<br>er has engineering | sembly with low responsibility. |  |
|---|--------------------------|---------------------------------|----------------------------|-------------------------|--|--|--------------|--------------------------------------|---|-----------------------|---------------------------------|--|---------------------------------|--|
|   |                          |                                 |                            | Form Type<br>Distribute | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Material |  |              |                                      |   | rials and N           | ls and Mfg Information          |  |                                 |  |
| Supplier Information                              |                          |                                 |                            |                         |  |  |              |                                      |   |                       |                                 |  |                                 |  |
| Company name* Con                                 |                          |                                 | Company unique ID          |                         |  | Unique ID Authority                    |              |                                      |   | Respor                | Response Date*                  |  |                                 |  |
| onsemi  |                          |                                 |                            |                         |  |  |              |                                      |   | 2023-06-08            |                                 |  |                                 |  |
| Contact Name                                      | act Name Title - Contact |                                 |                            |                         | Phone - Contact*   |  |              |                                      | Email   | Email - Contact*      |                                 |  |                                 |  |
| Product-Env-Stewards Product Enviro               |                          |                                 | ro Compliance              |                         |  | NA                                     |              |                                      |   | Produ                 | Product-Env-Stewards@onsemi.com |  |                                 |  |
| Authorized Representative* Title - Represe        |                          |                                 | sentative                  |                         |  | Phone - Representative*                |              |                                      |   | Email                 | Email - Representative*         |  |                                 |  |
| Product-Env-Stewards Prod                         |                          |                                 | Product Enviro Compliance  |                         |  | NA                                     |              |                                      |   | Produ                 | Product-Env-Stewards@onsemi.com |  |                                 |  |
| Requester Item Number                             | Mfr Item Number          |                                 | ber Mfr Item Name          |                         |  | Effective Date                         | Version      | М                                    | anufacturing Site                             |                       | Weight*                         | UOM  | Unit Type                       |  |
|   | MC100I                   | IC100LVEL34DR2G HF ECL CLOCK GI |                            | GEN                     |  | 2023-06-08 P                           |              | PH1                                  |   | 142.69                | mg                              | Each                                       |                                 |  |
| Aanufacturing Proccess Informat                   | tion                     |                                 | -                          |                         |  |  |              |                                      |   |                       |                                 |  |                                 |  |
| Terminal Plating / Grid Array Ma                  | terial 7                 | ial Terminal Base Alloy J       |                            | J-STD-020 MS            | L Rating   | Peak Proc                              | ess Body To  | ss Body Temperature Max Time at Peak |   | k Tempera             | ture Num                        | nber of Reflow Cyc                         | eles                            |  |
| Matte Tin (Sn) - annealed CU Alloy                |                          | CU Alloy                        |                            | 1                       |  | 260                                    |              | С                                    | 30  | seco                  | nds 3                           |  |                                 |  |
| omments   |                          |                                 |                            |                         |  |  |              |                                      |   |                       |                                 |  |                                 |  |
| vel 1 - maximum time at peak temperatu            | re during so             | ldering is 10-3                 | 0 seconds                  |                         |  |  |              |                                      |   |                       |                                 |  |                                 |  |
| or more information regarding material            | composition              | please refer to                 | page 3                     |                         |  |  |              |                                      |   |                       |                                 |  |                                 |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| sigma range of distribution unless | otherwise noted). |                 |          |                            |                  |        |        |                 |
|------------------------------------|-------------------|-----------------|----------|----------------------------|------------------|--------|--------|-----------------|
| Homogeneous Material               | Weight            | Unit of Measure | Level    | Substance                  | CAS              | Exempt | Weight | Unit of Measure |
| Die                                | 2.73              | mg              | Supplier | Silicon (Si)               | 7440-21-3        |        | 2.73   | mg              |
| Die Attach                         | 4.85              | mg              |          | Epoxy resin                | proprietary data |        | 0.485  | mg              |
|                                    |                   |                 | Supplier | Ethylene dimethacrylate    | 97-90-5          |        | 0.2425 | mg              |
|                                    |                   |                 | Supplier | Silver (Ag)                | 7440-22-4        |        | 3.88   | mg              |
|                                    |                   |                 | Supplier | Formaldehyde Polymer       | 9003-36-5        |        | 0.2425 | mg              |
| Lead Frame                         | 75.92             | mg              | Supplier | Silver (Ag)                | 7440-22-4        |        | 0.7592 | mg              |
|                                    |                   |                 | Supplier | Zinc (Zn)                  | 7440-66-6        |        | 0.1518 | mg              |
|                                    |                   |                 | Supplier | Iron (Fe)                  | 7439-89-6        |        | 1.9739 | mg              |
|                                    |                   |                 | Supplier | Copper (Cu)                | 7440-50-8        |        | 73.035 | mg              |
| Mold Compound-Black                | 55.11             | mg              |          | Epoxy resin                | proprietary data |        | 2.7555 | mg              |
|                                    |                   |                 | Supplier | Phenolic Resin             | Proprietary Data |        | 1.1022 | mg              |
|                                    |                   |                 | Supplier | Ortho Cresol Novolac Resin | 29690-82-2       |        | 1.3778 | mg              |
|                                    |                   |                 | Supplier | Carbon Black (C)           | 1333-86-4        |        | 0.2756 | mg              |
|                                    |                   |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0       |        | 49.599 | mg              |
| Plating                            | 3.73              | mg              | Supplier | Tin (Sn)                   | 7440-31-5        |        | 3.73   | mg              |
| Wire Bond - Au                     | 0.35              | mg              | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.35   | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).